

January 2014

# PN200A / MMBT200 PNP General-Purpose Amplifier

# **Description**

This device is designed for general-purpose amplifier applications at collector currents to 300 mA. Sourced from Process 68.



Figure 1. PN200A Device Package

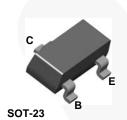


Figure 2. MMBT200 Device Package

# **Ordering Information**

Part Number	Marking	Package	Packing Method
PN200A	PN200A	TO-92 3L	Bulk
MMBT200	N2	SOT-23 3L	Tape and Reel

# Absolute Maximum Ratings(1),(2)

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. Values are at  $T_A = 25^{\circ}\text{C}$  unless otherwise noted.

Symbol	Parameter	Value	Unit
V <sub>CEO</sub>	Collector-Emitter Voltage	-45	V
V <sub>CBO</sub>	Collector-Base Voltage	-60	V
V <sub>EBO</sub>	Emitter-Base Voltage	-6	V
I <sub>C</sub>	Collector Current - Continuous	-500	mA
T <sub>J,</sub> T <sub>STG</sub>	Operating and Storage Junction Temperature Range	-55 to +150	°C

#### Notes

- 1. These ratings are based on a maximum junction temperature of 150°C.
- 2. These are steady-state limits. Fairchild Semiconductor should be consulted on applications involving pulsed or low-duty cycle operations.

## **Thermal Characteristics**

Values are at  $T_A = 25$ °C unless otherwise noted.

Symbol	Parameter	Ma	Unit	
	i diametei	PN200A <sup>(3)</sup>	MMBT200 <sup>(4)</sup>	Oilit
P <sub>D</sub>	Total Device Dissipation	625	350	mW
	Derate Above 25°C	5.0	2.8	mW/°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case	83.3		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	200	357	°C/W

### Notes:

- 3. PCB size: FR-4 76 x 114 x 1.57 mm<sup>3</sup> (3.0 inch x 4.5 inch x 0.062 inch) with minimum land pattern size.
- 4. Device mounted on FR-4 PCB 1.6 inch X 1.6 inch X 0.06 inch.

## **Electrical Characteristics**

Values are at  $T_A = 25$ °C unless otherwise noted.

Symbol	Parameter Conditions		s	Min.	Max.	Unit
Off Charact	teristics					
BV <sub>CBO</sub>	Collector-Base Breakdown Voltage $I_C = -10 \mu A, I_B = 0$		-60		V	
BV <sub>CEO</sub>	Collector-Emitter Breakdown Voltage <sup>(5)</sup>			-45		V
BV <sub>EBO</sub>	Emitter-Base Breakdown Voltage	$I_E = -10  \mu A,  I_C = 0$		-6.0		V
I <sub>CBO</sub>	Collector Cut-Off Current	$V_{CB} = -50 \text{ V}, I_{E} = 0$			-50	nA
I <sub>CES</sub>	Collector Cut-Off Current	$V_{CE} = -40 \text{ V}, I_{E} = 0$			-50	nA
I <sub>EBO</sub>	Emitter Cut-Off Current	V <sub>EB</sub> = -4.0 V, I <sub>C</sub> = 0			-50	nA
On Charact	eristics					
	DC Current Gain	I <sub>C</sub> = -100 μA, V <sub>CE</sub> = -1.0 V	MMBT200	80		
			PN200A	240		
		I <sub>C</sub> = -10 mA, V <sub>CE</sub> = -1.0 V	MMBT200	100	450	
h <sub>FE</sub>			PN200A	300	600	/
		$I_C = -100 \text{ mA},$ $V_{CE} = -1.0 \text{ V}^{(5)}$	PN200A	100		
		100 117 (5)	MMBT200	100	350	
			PN200A	100		
V <sub>CE</sub> (sat)	Collector-Emitter Saturation	I <sub>C</sub> = -10 mA, I <sub>B</sub> = -1.0 mA			-0.2	V
	Voltage	$I_C = -200 \text{ mA}, I_B = -20 \text{ mA}^{(5)}$			-0.4	V
V <sub>BE</sub> (sat)	Base-Emitter Saturation	I <sub>C</sub> = -10 mA, I <sub>B</sub> = -1.0 mA			-0.85	V
	Voltage	$I_C = -200 \text{ mA}, I_B = -20 \text{ mA}^{(5)}$			-1.00	
Small Signa	al Characteristics					
f <sub>T</sub>	Current Gain - Bandwidth Product	$V_{CE} = -20 \text{ V}, I_{C} = -20 \text{ mA},$		250		MHz
C <sub>ob</sub>	Output Capacitance	V <sub>CB</sub> = -10 V, f = -1.0 MHz			6.0	pF
NF	Noise Figure	$I_C = -100 \mu\text{A},  V_{CE} = -5.0 \text{V}, \ R_G = 2.0 \text{k}\Omega,  f = 1.0 \text{kHz}$			4.0	dB

#### Note:

5. Pulse test: pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2.0\%.$ 

# **Typical Performance Characteristics**

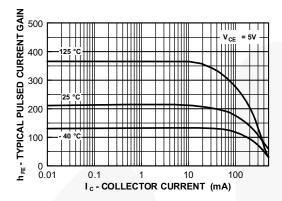


Figure 3. Typical Pulsed Current Gain vs. Collector Current

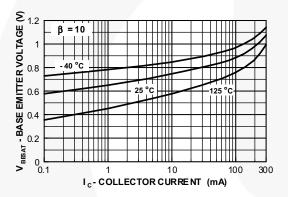


Figure 5. Base-Emitter Saturation Voltage vs. Collector Current

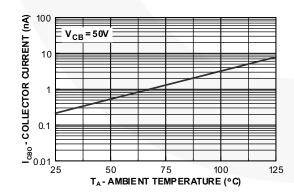


Figure 7. Collector Cut-Off Current vs.
Ambient Temperature

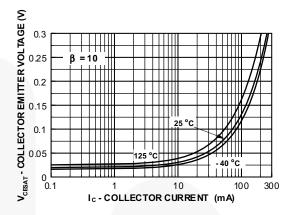


Figure 4. Collector-Emitter Saturation Voltage vs. Collector Current

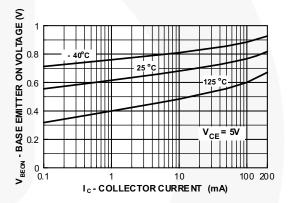


Figure 6. Base-Emitter On Voltage vs. Collector Current

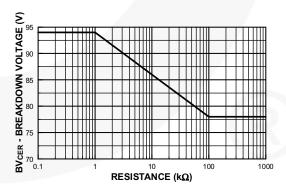


Figure 8. Collector-Emitter Breakdown Voltage with Resistance Between Emitter-Base

# **Typical Performance Characteristics** (Continued)

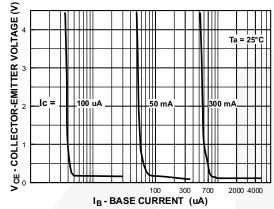


Figure 9. Collector Saturation Region

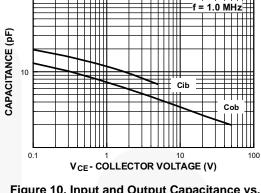


Figure 10. Input and Output Capacitance vs. Reverse Voltage

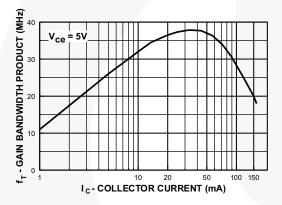


Figure 11. Gain Bandwidth Product vs. Collector Current

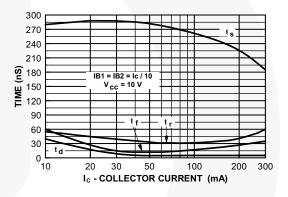


Figure 12. Switching Times vs. Collector Current

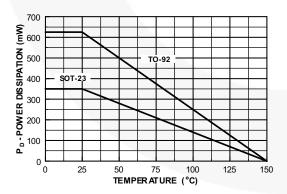


Figure 13. Power Dissipation vs. Ambient Temperature

# **Physical Dimensions**

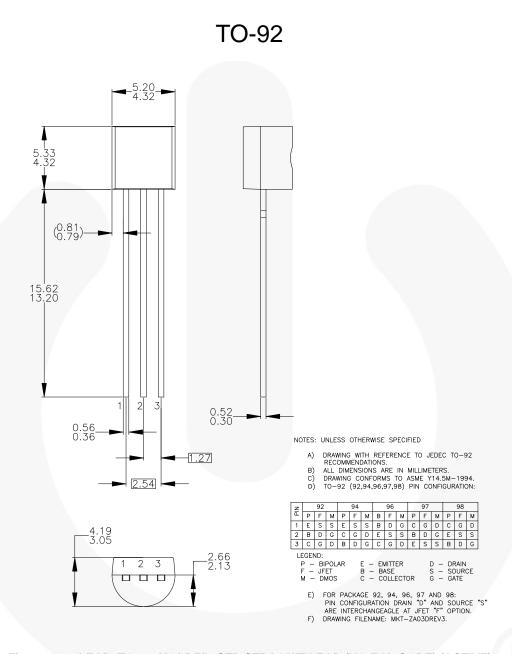


Figure 14. 3-LEAD, TO-92, MOLDED, STD STRAGHIT LEAD (NO EOL CODE) (ACTIVE)

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings: http://www.fairchildsemi.com/dwq/ZA/ZA03D.pdf.

For current tape and reel specifications, visit Fairchild Semiconductor's online packaging area: <a href="http://www.fairchildsemi.com/packing\_dwg/PKG-ZA03D\_BK.pdf">http://www.fairchildsemi.com/packing\_dwg/PKG-ZA03D\_BK.pdf</a>.

## Physical Dimensions (Continued)

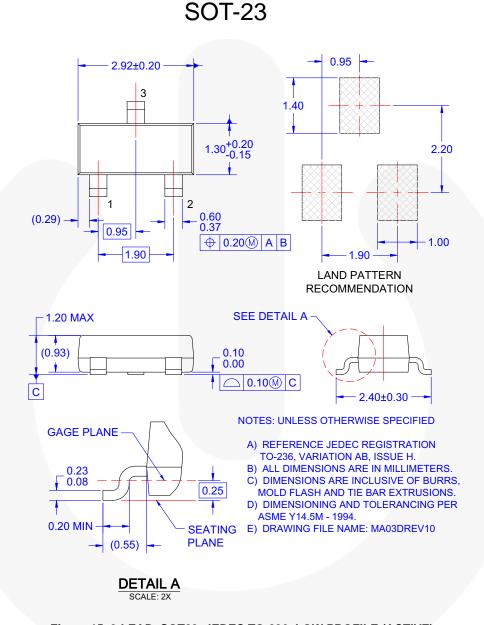


Figure 15. 3-LEAD, SOT23, JEDEC TO-236, LOW PROFILE (ACTIVE)

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings: <a href="http://www.fairchildsemi.com/dwg/MA/MA03D.pdf">http://www.fairchildsemi.com/dwg/MA/MA03D.pdf</a>.

For current tape and reel specifications, visit Fairchild Semiconductor's online packaging area: <a href="http://www.fairchildsemi.com/packing\_dwg/PKG-MA03D.pdf">http://www.fairchildsemi.com/packing\_dwg/PKG-MA03D.pdf</a>.





#### **TRADEMARKS**

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

AccuPower™ F-PFS™ AX-CAP®, **FRFET®** Global Power Resource<sup>SM</sup> BitSiC™ Build it Now™ GreenBridge™ CorePLUS™ Green FPS™ CorePOWER™ Green FPS™ e-Series™ Gmax™  $CROSSVOLT^{\text{\tiny TM}}$ GTO™  $\mathsf{CTL}^{\mathsf{TM}}$ IntelliMAX™

Current Transfer Logic™ IntelliMAX™

DEUXPEED® ISOPLANAR™

Dual Cool™ Making Small Speakers Sound Louder

EcoSPARK® and Better™

EfficientMax™ MegaBuck™

ESBC™ MICROCOUPLER™

MicroFET™

Tairchild® MicroPak™ MicroPak™
Fairchild Semiconductor® MillerDrive™
FACT Quiet Series™ MotionMax™
FACT® mWSaver®
FAST® OptoHiT™

FAST® mWSaver®
FAST® OptoHiT™
FastvCore™ OPTOLOGIC®
FETBench™ OPTOPLANAR®
FPS™

PowerTrench<sup>®</sup> PowerXS™

Programmable Active Droop™

QFET<sup>®</sup>
QS™
Quiet Series™
RapidConfigure™

Saving our world, 1mW/W/kW at a time™

SignalWise™ SmartMax™ SMART START™

Solutions for Your Success™

SPM®
STEALTH™
SuperFET®
SuperSOT™-3
SuperSOT™-6
SuperSOT™-8
SupreMOS®
SyncFET™

Sync-Lock™

SYSTEM

GENERAL®\*

TinyBoost®

TinyBuck®

TinyCalc™

TinyLogic®

TINYOPTO™

TinyPower™

TinyPower™

TinyPWire™

TranSiC™

TriFault Detect™

TRUECURRENT®\*

µSerDes™

SerDes\*
UHC®
UItra FRFET™
UniFET™
VCX™
VisualMax™
VoltagePlus™
XS™

#### **DISCLAIMER**

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN, NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

## LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

- 1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
- A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

#### ANTI-COUNTERFEITING POLICY

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.fairchildsemi.com, under Sales Support.

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufacturers of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed applications, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handling and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address any warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

#### PRODUCT STATUS DEFINITIONS

#### **Definition of Terms**

Definition of Terms				
<b>Datasheet Identification</b>	Product Status	Definition		
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.		
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.		
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.		
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.		

Rev. 166

<sup>\*</sup> Trademarks of System General Corporation, used under license by Fairchild Semiconductor.